


## Standardized Information Note (IN)

| 1. Information Note basic data |  |
|--------------------------------|--|
| 1.1 Company                    |  TAIWAN SEMICONDUCTOR |
| 1.2 Information Note No.       | IN17033  |
| 1.3 Title of IN                | Add instructions of MSL 3 (Moisture Sensitivity Level) for Package TO-252&TO-223 on Datasheet Note     |
| 1.4 Issue date                 | 2017/10/20   |

| 2. Contact                   |                          |                          |
|------------------------------|--------------------------|--------------------------|
| 2.1 Contact supplier         |                          |                          |
| 2.1.1 Name                   | Sunnie Lin               |                          |
| 2.1.2 Phone                  | 886-2-8913-1588 Ext.2205 |                          |
| 2.1.3 Email                  | Sunnie@mail.ts.com.tw    |                          |
| 2.2 Team supplier (optional) |                          |                          |
| 2.2.1 Name (optional)        | 2.2.2 Phone (optional)   | 2.2.3 Email (optional)   |
| Danny Lin                    | 886-2-8913-1588 Ext.2133 | Danny_lin@mail.ts.com.tw |
|                              |                          |                          |
|                              |                          |                          |

| 3. Description |   |   |
|----------------|---|---|
|                | Old   | New   |
| Description #1 | In the note of datasheet , Moisture Sensitivity Level per J-STD-020.<br>Notes: MSL 3 (Moisture Sensitivity Level) per J-STD-020 | In the note of datasheet , Moisture Sensitivity Level per J-STD-020.<br>Notes: MSL 3 (Moisture Sensitivity Level) for TO-252 (D-PAK) per J-STD-020<br><br>TSM1NB60 Datasheet Notes: MSL 3 (Moisture Sensitivity Level) for TO-252 (D-PAK),SOT-223 per J-STD-020 |
| Description #2 |   |   |
| Description #3 |   |   |
| Description #4 |   |   |
| Description #5 |   |   |

| 4. Reason / motivation                |  |
|---------------------------------------|--|
| 4.1 Motivation                        | Aligned the MSL rating on the datasheet for appropriate package (SMD, Surface Mount device). |
| 4.2 Additional explanation (optional) |  |

| 5. Marking of parts / traceability |     |
|------------------------------------|-----|
| 5.1 Description                    | N/A |

| 6. Timing / schedule           |     |
|--------------------------------|-----|
| 6.1 Intended start of delivery | N/A |

| 7. Attachments (e.g. additional documentation, pictures, part list...)  |
|---|
| Refer to the official e-mail announcement for the applicable documents. |

